

RECOMMENDED HOLE PATTERN
TOLERANCE ±0.05



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spec ref		dr	Guo-Min Sun	2013/12/23	projection	mm	size	A3	scale	5:1
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Guo-Min Sun	2014/09/03	ecn no	ELX-N-18717-1	
		chr	-	-	product family		rel level		Released	
		appr	Rick Bian	2014/09/04	MINITEK 2.0mm HEADER		dwg no		10127616	
surface ✓		linear	0.X	±0.50	BTB THRU-HOLE LOSE PIN TYPE		rev		B	
			0.XX	±0.25	www.fci.com		cat. no.		Product - Customer Drw	
			0.XXX	±0.15			sheet 1 of 2			
		angular	0°	±3°						

PRODUCT NUMBER DESCRIPTION:
10127616 - X XX X XX LF

PLATING: _____
1 = 15u" GXT ON CONTACT;
2 = 30u" GXT ON CONTACT;
3 = 80~200u" Tin ON CONTACT;

LEAD FREE

LOSE PIN POSITION	
01	7,8,15,16
02	7,8,15,16,23,24

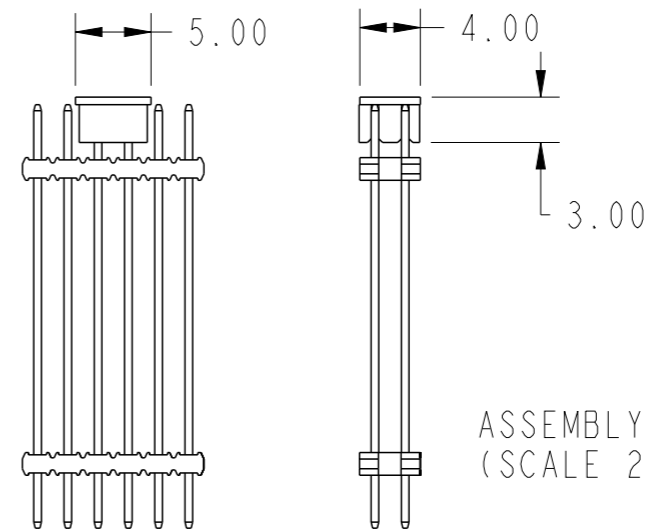
PACKAGING:
A = TUBE WITH PICK-UP CAP

POSITIONS PER ROW = "N"
(02 ~ 25)

NOTES:

- MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL 94V-0, COLOR BLACK
- MATERIAL TERMINAL: COPPER ALLOY
- TO DETERMINE DIMENSIONS:
N=NUMBER OF POSITIONS PER ROW
EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS
- 0.2kg MIN PER PIN RETENTION IN EITHER DIRECTION.
- DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN,
DIM 1.5 MAX APPLIES.
- P/N:10127616-XXXLF IS SAME AS P/N:10127616-XXX. THE SUFFIX 'LF'
IS ADDED FOR EASY LEAD FREE IDENTIFICATION.

- THE HOUSING WILL WITHSTAND EXPOSURE TO 255~C PEAK
TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260~C PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



dr	Guo-Min Sun	2013/12/23	projection	mm	size	A3	scale	8:1
eng	Guo-Min Sun	2014/09/03			ecn no			
chr	-	-			ELX-N-18717-1			
appr	Rick Bian	2014/09/04	product family	-	rel level			
			MINITEK 2.0mm HEADER		dwg no	10127616		rev
www.fci.com			BTB THRU-HOLE LOSE PIN TYPE				B	
cat. no.			-		Product - Customer Drw		sheet 2 of 2	